

10/691,136

L Number	Hits	Search Text	DB	Time stamp
1	71	((waveguide near8 (microns micrometers)) and @ad<20031021) and (solder near6 (ball bump column))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/28 11:34
2	96	((conductive adj bump) near8 temperature) and solder and bond\$3 and @ad<20031021	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/28 11:36
-	2075	(waveguide near8 (microns micrometers)) and @ad<20031021	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/27 19:06
-	181	((waveguide near8 (microns micrometers)) and @ad<20031021) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/27 19:06
-	150	((waveguide near8 (microns micrometers)) and @ad<20031021) and solder) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/27 19:06
-	71	((waveguide near8 (microns micrometers)) and @ad<20031021) and (solder near6 (ball bump column))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/27 19:07
-	71	((waveguide near8 (microns micrometers)) and @ad<20031021) and (solder near6 (ball bump column))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/10/28 11:22